

Title (en)

MATERIAL FOR ELECTRIC CONTACTS AND PROCESS FOR MANUFACTURING CONTACTS, AND THE MANUFACTURED CONTACT PART

Publication

**EP 0152606 A3 19850925 (DE)**

Application

**EP 84115754 A 19841218**

Priority

- DE 3403115 A 19840130
- DE 3428070 A 19840730

Abstract (en)

[origin: US4565590A] The invention relates to a material for electrical contacts, in particular for contact studs in low-voltage switchgear. The material consists of silver, tin oxide and other additives. A material is sought where the overtemperature is lowered as compared with known AgSnO<sub>2</sub> material. According to the invention, the further additives are in combination oxides of the metals tantalum (Ta<sub>2</sub>O<sub>5</sub>), copper (CuO) and bismuth (Bi<sub>2</sub>O<sub>3</sub>). Further the material may contain also tungsten or oxygen containing tungsten compounds. Preferably the material contains 5 to 20 mass % SnO<sub>2</sub>, 0.1 to 5 mass % Ta<sub>2</sub>O<sub>5</sub> 5 mass % CuO, 0.1 to 5 mass % Bi<sub>2</sub>O<sub>3</sub>, optionally 0.05 to 3 mass % tungsten and silver as balance. In the method for producing contact studs, the powder metallurgical production of the material is followed by extrusion to a ribbon, from which contact studs can be separated which have an edge-parallel directional structure.

IPC 1-7

**H01H 1/02**

IPC 8 full level

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Citation (search report)

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